

# Cross section of CMOS7SF Technology ( 3 levels of metal, wirebond option ) DV post etch

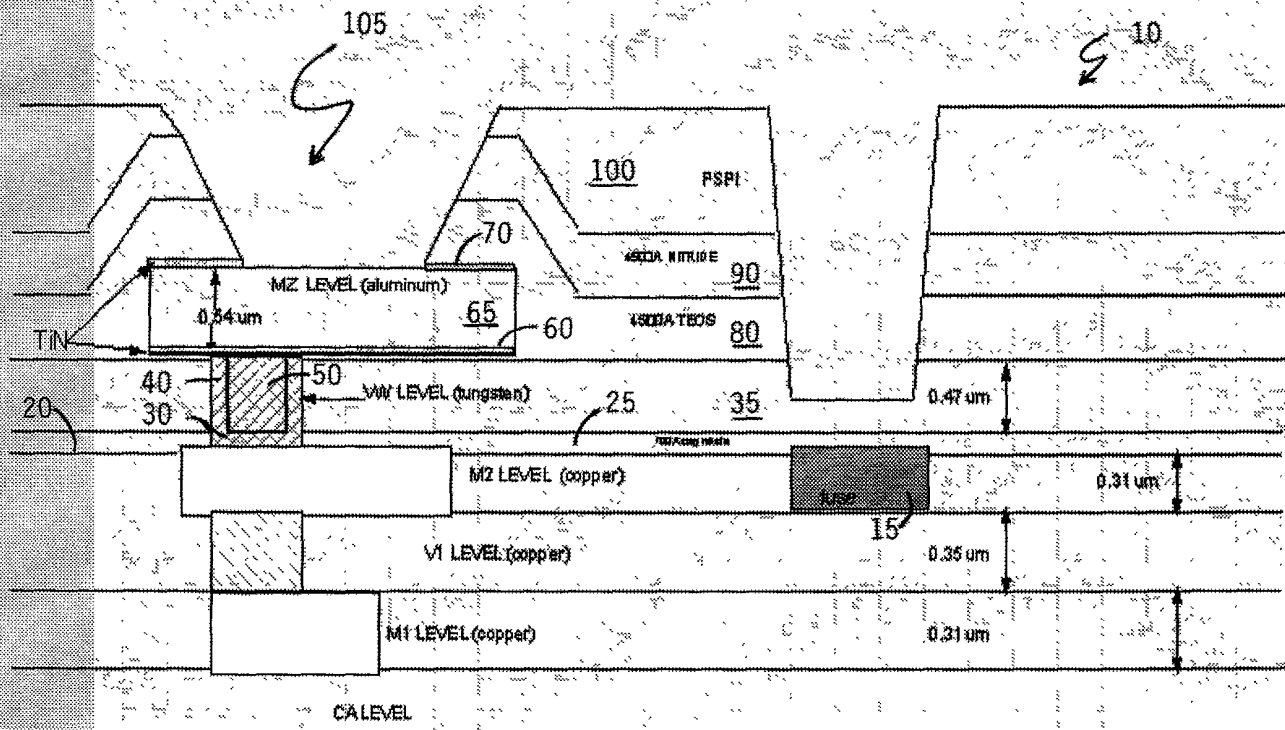


FIGURE 1

# Cross section of CMOS7SF Technology 3 levels of metal, using W via and aluminum last metal

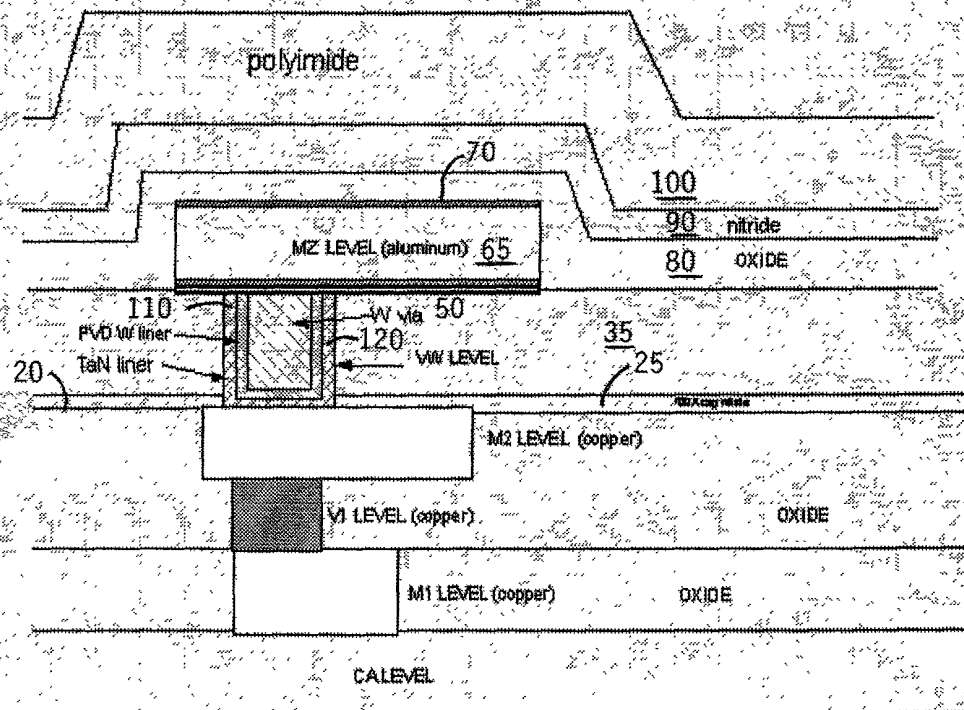


FIGURE 2